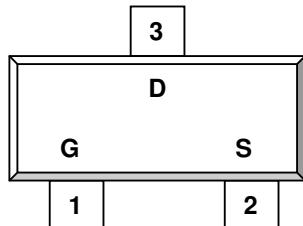
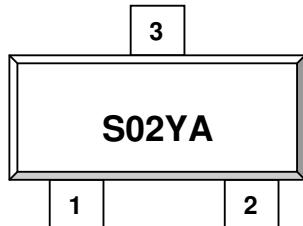


DESCRIPTION

G2302 is the N-Channel logic enhancement mode power field effect transistor which is produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management, other battery powered circuits, and low in-line power loss are required. The product is in a very small outline surface mount package.

PIN CONFIGURATION
SOT-23


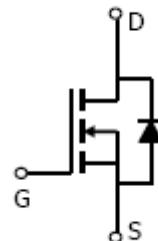
1.Gate 2.Source 3.Drain

PART MARKING
SOT-23


Y: Year Code A: Process Code

FEATURE

- 20V/3.6A, $R_{DS(ON)} = 70m\Omega$ @ $VGS = 4.5V$
- 20V/3.1A, $R_{DS(ON)} = 95 m\Omega$ @ $VGS = 2.5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- SOT-23 package design

**ORDERING INFORMATION**

Part Number	Package	Part Marking
G2302	SOT-23	S02YA

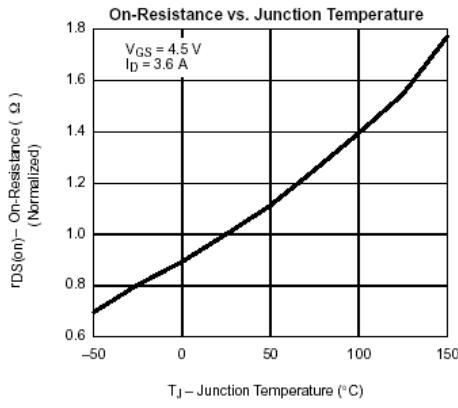
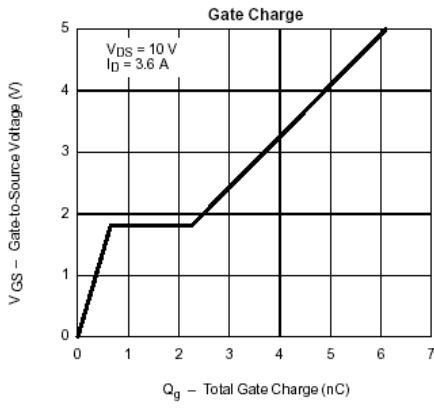
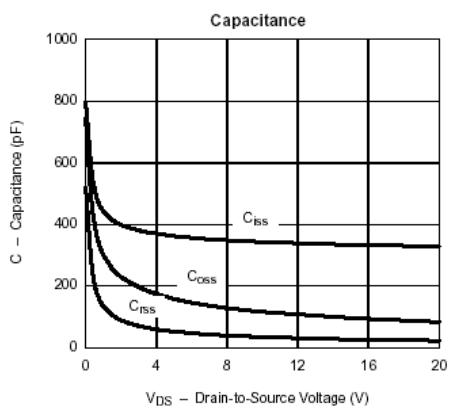
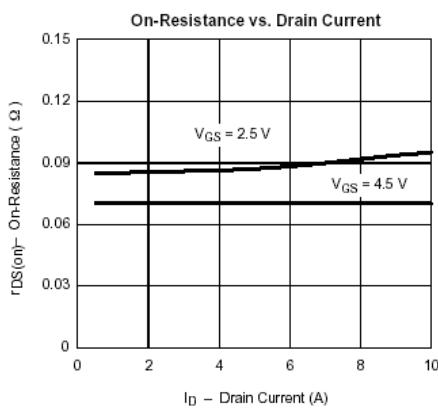
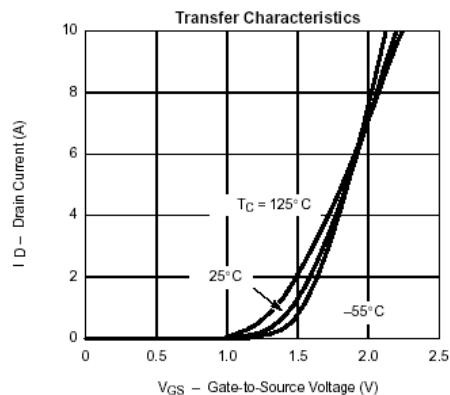
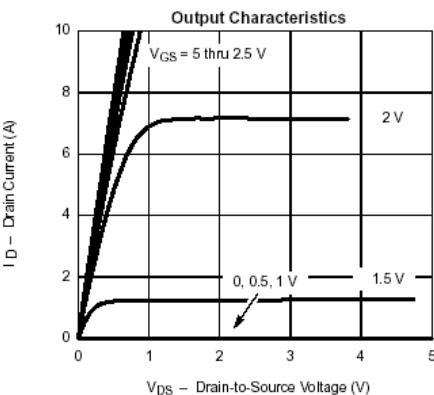
※ Process Code : A ~ Z ; a ~ z

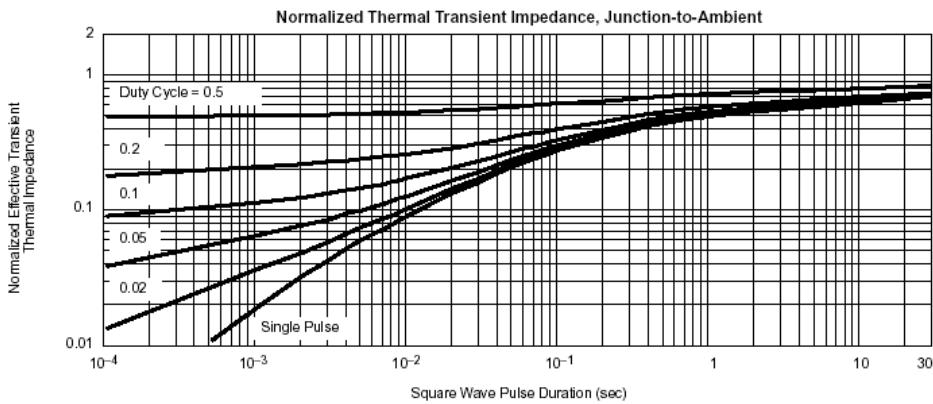
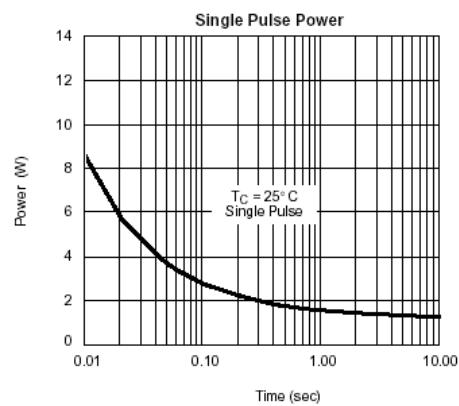
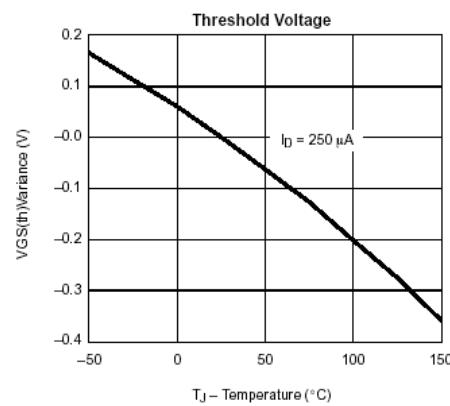
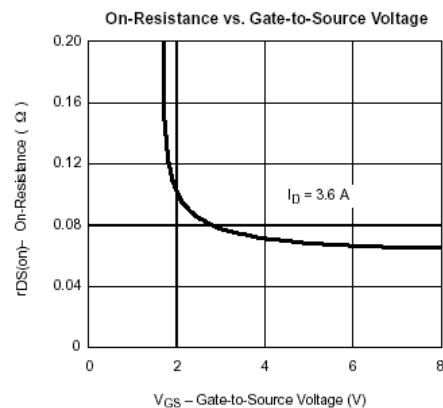
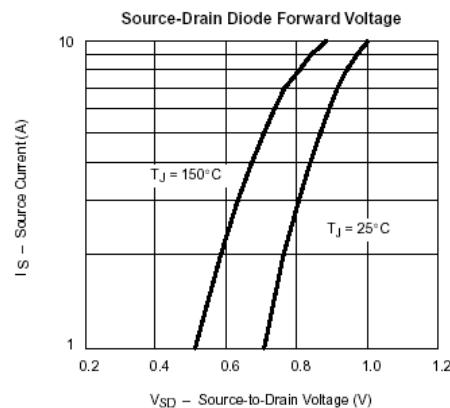
GTM**ABSOLUTE MAXIMUM RATINGS (Ta = 25°C Unless otherwise noted)**

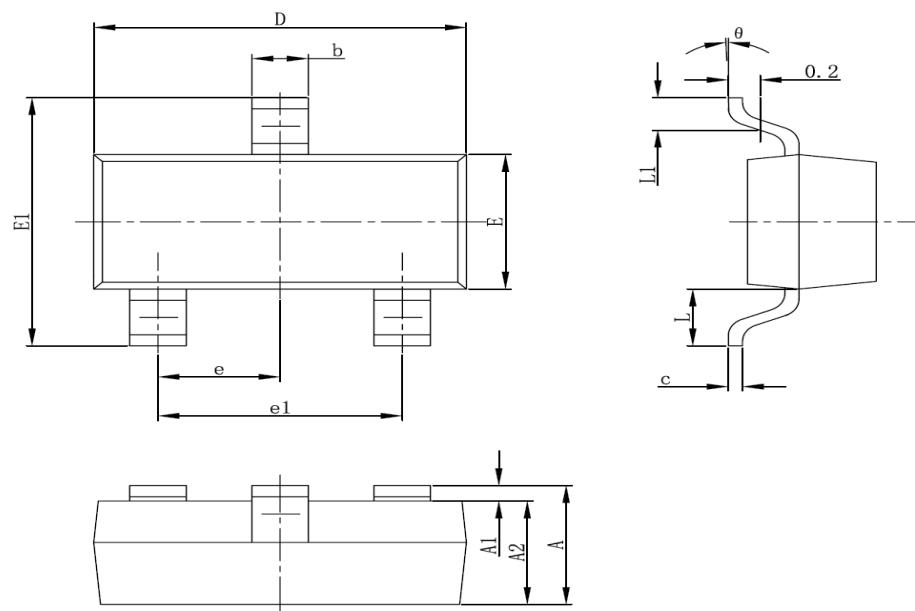
Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V _{DSS}	20	V
Gate-Source Voltage	V _{GSS}	±12	V
Continuous Drain Current(T _J =150°C)	I _D	3.6 2.6	A
Pulsed Drain Current	I _{DM}	10	A
Continuous Source Current (Diode Conduction)	I _S	1.6	A
Power Dissipation	P _D	1.25 0.8	W
Operation Junction Temperature	T _J	150	°C
Storage Temperature Range	T _{STG}	-55/150	°C
Thermal Resistance-Junction to Ambient	R _{θJA}	100	°C/W

GTM**ELECTRICAL CHARACTERISTICS (Ta = 25°C Unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit	
Static							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =-250uA	20			V	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA	0.4		1.0	V	
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±12V			±100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =20V, V _{GS} =0V			1	uA	
		V _{DS} =20V, V _{GS} =0V T _J =55°C			10		
Drain-source On-Resistance	R _{D(S(on))}	V _{GS} =4.5V, I _D =3.6A V _{GS} =2.5V, I _D =3.1A		0.070 0.095		Ω	
Forward Transconductance	g _{fs}	V _{DS} =5V, I _D =3.6V		10		S	
Diode Forward Voltage	V _{SD}	I _S =1.6A, V _{GS} =0V		0.85	1.2	V	
Dynamic							
Total Gate Charge	Q _g	V _{DS} =10V V _{GS} =4.5V I _D ≡3.6A		5.4	10	nC	
Gate-Source Charge	Q _{gs}			0.65			
Gate-Drain Charge	Q _{gd}			1.4			
Input Capacitance	C _{iss}	V _{DS} =10V V _{GS} =0V F=1MHz		340		pF	
Output Capacitance	C _{oss}			115			
Reverse Transfer Capacitance	C _{rss}			33			
Turn-On Time	t _{d(on)} tr	V _{DD} =10V R _L =5.5Ω I _D =3.6A V _{GEN} =4.5V R _G =6Ω		12	25	nS	
				36	60		
Turn-Off Time	t _{d(off)} tf			34	60		
				10	25		

GTM**3.6A N Channel Enhancement Mode MOSFET****TYPICAL CHARACTERISTICS (25°C Unless noted)**

TYPICAL CHARACTERISTICS (25°C Unless noted)

SOT-23 PACKAGE OUTLINE

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950TYP		0.037TYP	
e1	1.800	2.000	0.071	0.079
L	0.550REF		0.022REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°